

Technical Explanation Board 4s SKYPER® 32 R

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Please note:

All values in this technical explanation are typical values. Typical values are the average values expected in large quantities and are provided for information purposes only. These values can and do vary in different applications. All operating parameters should be validated by user's technical experts for each application.



1. Application and Handling Instructions

- Please provide for static discharge protection during handling. As long as the hybrid driver is not
 completely assembled, the input terminals have to be short-circuited. Persons working with devices
 have to wear a grounded bracelet. Any synthetic floor coverings must not be statically chargeable. Even
 during transportation the input terminals have to be short-circuited using, for example, conductive
 rubber. Worktables have to be grounded. The same safety requirements apply to MOSFET- and IGBTmodules.
- Any parasitic inductances within the DC-link have to be minimised. Over-voltages may be absorbed by C- or RCD-snubber networks between main terminals for PLUS and MINUS of the power module.
- When first operating a newly developed circuit, SEMIKRON recommends to apply low collector voltage
 and load current in the beginning and to increase these values gradually, observing the turn-off
 behaviour of the free-wheeling diode and the turn-off voltage spikes generated across the IGBT. An
 oscillographic control will be necessary. Additionally, the case temperature of the module has to be
 monitored. When the circuit works correctly under rated operation conditions, short-circuit testing may
 be done, starting again with low collector voltage.
- It is important to feed any errors back to the control circuit and to switch off the device immediately in failure events. Repeated turn-on of the IGBT into a short circuit with a high frequency may destroy the device.
- The inputs of the hybrid driver are sensitive to over-voltage. Voltages higher than VS +0,3V or below -0,3V may destroy these inputs. Therefore, control signal over-voltages exceeding the above values have to be avoided.
- The connecting leads between hybrid driver and the power module should be as short as possible (max. 20cm), the driver leads should be twisted.

2. Further application support

Latest information is available at http://www.semikron.com. For design support please read the SEMIKRON Application Manual Power Modules available at http://www.semikron.com.

3. General Description

The Board 4s SKYPER® 32 R is an adaptor board for the IGBT module SEMiX® 4s (spring contact version). The board can be customized allowing adaptation and optimization to the used SEMiX® Module. The switching characteristic of the IGBT can be influenced through user settings, e.g. changing turn-on and turn-off speed by variation of R_{Gon} and R_{Goff} . Furthermore, it is possible to adjust the monitoring level and blanking time for the DSCP (see Technical Explanations SKYPER® 32 R).

Please note:

This technical explanation is based on the Technical Explanations for SKYPER[®] 32 R. Please read the Technical Explanations SKYPER[®] 32 R before using the Adaptor Board.

Figure 1: Board 4s SKYPER® 32 R



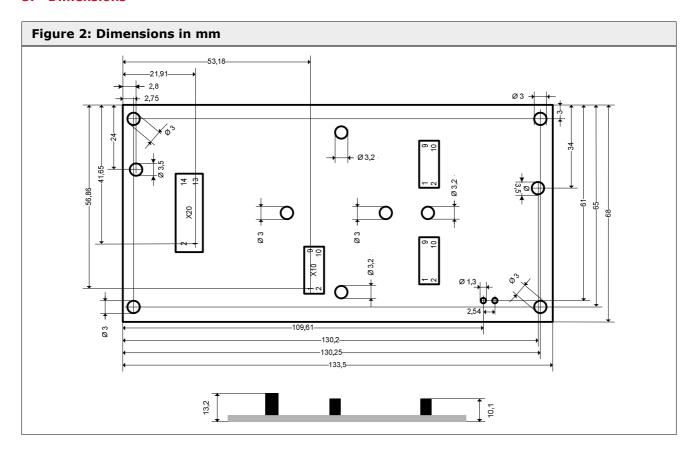


4. Quality

| Table 1: Quality | | | | |
|------------------|------------------------------|--|----------------|--|
| End test | test category | test describtion | standard | |
| AOI | Automated Optical Inspection | Control of accurate placement of components/ of solder joints | SEMIKRON | |
| ICT | In-Circuit Test | Test of the populated PCB, checking the correctly fabrication | SEMIKRON | |
| Type test | test category | test conditions | standard | |
| EP | Electrical Parameters | Jamb = -40°C / +85°C | SEMIKRON | |
| SP | STEP Test, Interrupted PS | 20x 10μs to 2s | EN61000-4-29 | |
| Iso | Isolation Test | High voltage test 4kV, 60s | EN 61800-5-1 | |
| TC | Thermal Cycling | 200 cycles, Tstgmax – Tstgmin | IEC60068-2-14 | |
| PD | Partial discharge test | >1,2 kV; suitable for 1000V DC Link | VDE 0110-20 | |
| TH | Temperature Humidity | 85°C, 85% RH, 96h | IEC 60068-2-67 | |
| VB | Vibration | Sinus 20/2000Hz Random 10/2000Hz, 5g, 26 per x,y,z | IEC 60068-2-6 | |
| SH | Shock | Half-sinus pulse, 30g, 6000 shocks, 6ms, $\pm x$, $\pm y$, $\pm z$ | IEC 60068-2-29 | |

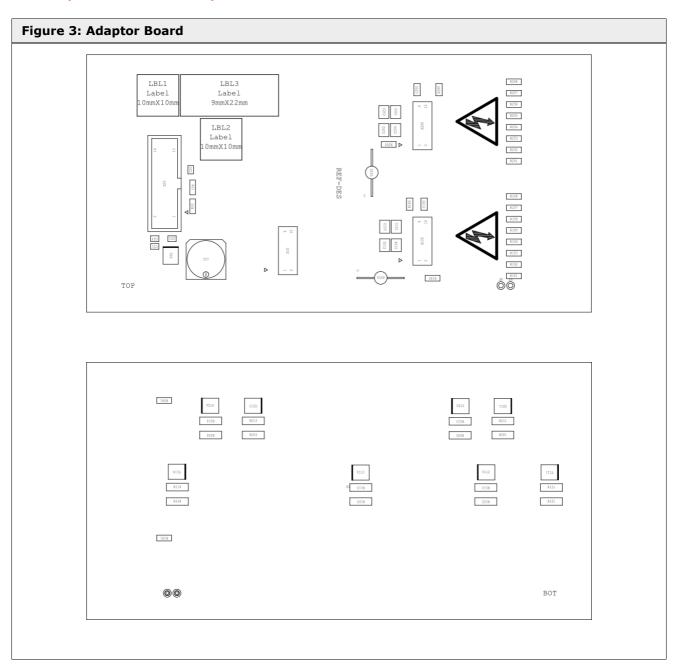


5. Dimensions

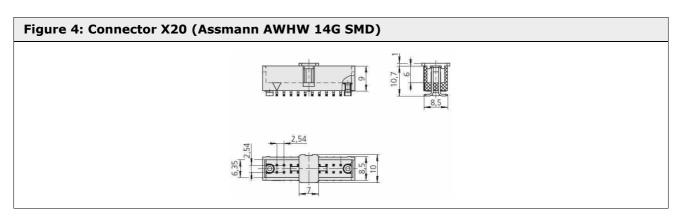




6. Component Placement Layout



7. PIN Array





Product information of suitable female connectors and distributor contact information is available at e.g. http://www.harting.com (part number 09 18 514 6 813).

| Table 2: PIN Array | | | | |
|--------------------|---------------|--|--|--|
| PIN | Signal | Function | Specification | |
| X20:01 | reserved | | | |
| X20:02 | IF_HB_BOT | Switching signal input (BOTTOM switch) | Digital 15 V; 10 kOhm impedance; LOW = BOT switch off; HIGH = BOT switch on | |
| X20:03 | IF_nERROR_OUT | ERROR output | LOW = NO ERROR; open collector output; max. 30V / 15mA (external pull up resistor necessary) | |
| X20:04 | IF_HB_TOP | Switching signal input (TOP switch) | Digital 15 V; 10 kOhm impedance; LOW = TOP switch off; HIGH = TOP switch on | |
| X20:05 | reserved | | | |
| X20:06 | reserved | | | |
| X20:07 | reserved | | | |
| X20:08 | IF_PWR_15P | Drive power supply | Stabilised +15V ±4% | |
| X20:09 | IF_PWR_15P | Drive power supply | Stabilised +15V ±4% | |
| X20:10 | IF_PWR_GND | GND for power supply and GND for digital signals | | |
| X20:11 | IF_PWR_GND | GND for power supply and GND for digital signals | | |
| X20:12 | reserved | | | |
| X20:13 | reserved | | | |
| X20:14 | reserved | | | |

Please note:

The feature PRIM_ERROR_IN of the driver core is not availble at the interface X20.



8. Setting Dynamic Short Circuit Protection

| Table 3: R _{CE} & C _{CE} | | | |
|--|--------------|--|-----|
| Designation | Pattern Name | Setting | |
| R160 | 1206 | R _{CE} Factory setting: not equipped | ТОР |
| C150 | 1206 | C _{CE} Factory setting: not equipped | ТОР |
| R260 | 1206 | R _{CE} Factory setting: not equipped | вот |
| C250 | 1206 | C _{CE} Factory setting: not equipped | вот |

9. Collector Series Resistance

| Table 4: R _{VCE} | | | |
|---------------------------|--------------|--|-----|
| Designation | Pattern Name | Setting | |
| R150 | MiniMELF | R _{VCE} * Factory setting: not equipped | ТОР |
| R250 | MiniMELF | R _{VCE} * Factory setting: not equipped | ВОТ |

* 1200V IGBT operation: 0Ω 1700V IGBT operation: $1k\Omega$ / 0,4W

10. Adaptation Gate Resistors

| Table 5: R _{Gon} & R _{Goff} | | | |
|--|--------------|--|-----|
| Designation | Pattern Name | Setting | |
| R151, R152, R153, R154 (parallel connected) | MiniMELF | R _{Gon} Factory setting: not equipped | ТОР |
| R155, R156, R157, R158 (parallel connected) | MiniMELF | R _{Goff} Factory setting: not equipped | ТОР |
| R251, R252, R253, R254 (parallel connected) | MiniMELF | R _{Gon} Factory setting: not equipped | вот |
| R255, R256, R257, R258 (parallel connected) | MiniMELF | R _{Goff} Factory setting: not equipped | вот |



11. Adaptation Decoupling Gate Resistors

For details to the decoupling gate resistors and recommended values, see Modules Explanations and Data Sheets SEMiX $^{\otimes}$.

| Table 6: R _{G1} , R _{G2} , R _{G3} R _{G4} | | | |
|--|--------------|--|-----|
| Designation | Pattern Name | Setting | |
| R101 | MELF | $R_{\rm G1}$ Factory setting: not equipped | ТОР |
| R102 | MELF | $R_{\rm G2}$ Factory setting: not equipped | ТОР |
| R103 | MELF | R _{G3} Factory setting: not equipped | ТОР |
| R104 | MELF | R _{G4} Factory setting: not equipped | ТОР |
| R201 | MELF | R _{G1} Factory setting: not equipped | ВОТ |
| R202 | MELF | R _{G2} Factory setting: not equipped | ВОТ |
| R203 | MELF | R _{G3} Factory setting: not equipped | ВОТ |
| R204 | MELF | R _{G4} Factory setting: not equipped | ВОТ |

12. Boost Capacitors

| Table 7: C _{boost15P} & C _{boost8N} | | | |
|---|--------------|---|-----|
| Designation | Pattern Name | Setting | |
| C151 | 1210 | C _{boost8N} Factory setting: 4,7µF/16V * | ТОР |
| C152 | 1210 | C _{boost15P} Factory setting: 2,2µF/25V * | ТОР |
| C251 | 1210 | C _{boost8N} Factory setting: 4,7µF/16V * | ВОТ |
| C252 | 1210 | C _{boost15P} Factory setting: 2,2µF/25V * | ВОТ |

^{*} output charge pulse: $5\mu C$



13. Temperature Signal

The temperature sensor inside the SEMiX $^{\otimes}$ module is directly connected to contacting points T1 and T2. For details to the temperature sensor, see Modules Explanations SEMiX $^{\otimes}$.

Safety Warnings:



The contacting points T1 and T2 are not electrical isolated. Due to high voltage that may be present at the contacting points T1 and T2, some care must be taken in order to avoid accident. There is no cover or potential isolation that protect the high voltage sections / wires from accidental human contact.

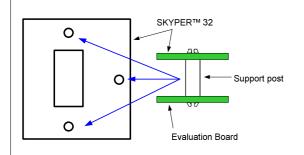
14. Mounting Notes

The electrical connections between adaptor board and SEMiX $^{(8)}$ are realised via spring contacts integrated in SEMiX $^{(8)}$ power modules and via landing pads on the bottom side of the adaptor board.

Figure 5: Adaptor Board & Driver Core Mounting



- [1] Soldering of components (e.g. R_{Gon}, R_{Goff}, etc.) on adapter board.
- [2] Adaptor Board has to be fixed to the SEMiX® module (see "Mounting Instruction and Application Notes for SEMiX® IGBT modules" on SEMiX® product overview page at http://www.semikron.com).
- [3] Insert driver core into the box connector on adaptor board.

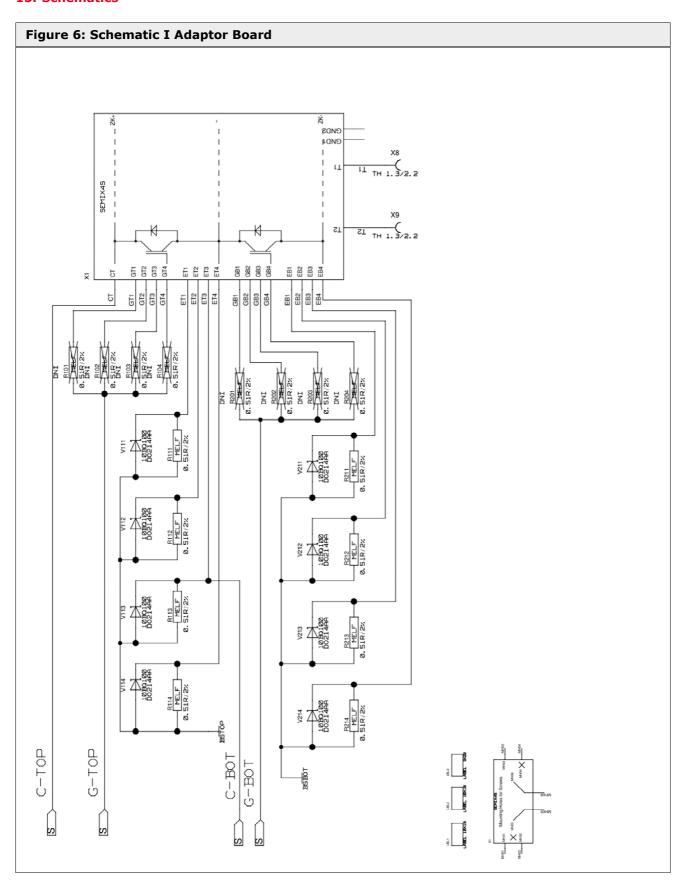


The connection between driver core and adaptor board should be mechanical reinforced by using support posts. The posts have to be spaced between driver core and adaptor board.

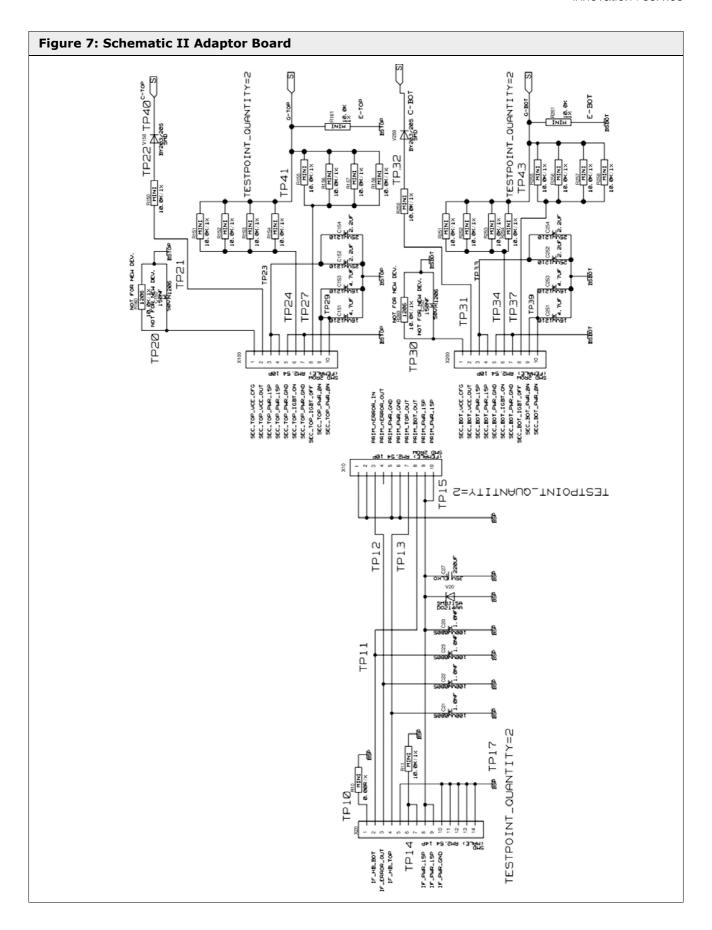
Product information of suitable support posts and distributor contact information is available at e.g. http://www.richco-inc.com (e.g. part number DLMSPM-8-01, LCBST-8-01).



15. Schematics









16. Parts List

Figure 8: Parts List Adaptor Board

| Count | Ref. Designator | Value | Pattern Name | Description |
|-------|---|-------------|----------------|--------------------|
| 4 | C151, C153, C251, C253 | 4,7µF | 1210 (SMD) | Capacitor X7R |
| 4 | C152, C154, C252, C254 | 2,2µF | 1210 (SMD) | Capacitor X7R |
| 4 | C20, C21, C22, C23 | 1nF | 0805 (SMD) | Capacitor X7R |
| 1 | C27 | 220uF/35V | SMD | Longlife-Elko |
| 1 | R10 | 0,00Ohm | MiniMelf (SMD) | |
| 3 | R11, R161, R261 | 10,0KOhm | MiniMelf (SMD) | 1% |
| 8 | R111, R112, R113, R114, R211, R212, R213, R214 | 0,51Ohm | Melf (SMD) | 2% |
| 8 | V111, V112, V113, V114, V211, V212, V213, V214 | 10BQ100N | DO214AA (SMD) | Diode Schottky |
| 2 | V150, V250 | BY203/20S | | High Voltage Diode |
| 1 | V20 | SMBJ15A | DO215AA (SMD) | Suppressor Diode |
| 3 | X10, X100, X200 | RM2,54 10p. | SMD | Box Connector |
| 1 | X20 | 14p. | SMD | Connector |

TP: Test Point

Box Connector: SUYIN 254100FA010G200ZU



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References

- [1] www.SEMIKRON.com
- [2] A. Wintrich, U. Nicolai, W. Tursky, T. Reimann, "Application Manual Power Semiconductors", ISLE Verlag 2011, ISBN 978-3-938843-666

HISTORY

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